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PRODUCT NO.	NO. OF POS	LOADED POS	HSG COLOR
61835-X441	4	ALL POS	BLACK
-X421	4	3,4	BLACK
-X442	4	ALL POS	GRAY
-X422 -	4	3,4	GRAY

PLATING CODE X	PLATING	
0	5u" Au + high performance lubricant	
1	15 u" GOLD	
3	30 u "GOLD	
4	6 u "GOLD	
5	50 u "GOLD	

7.62

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BOARD LAYOUT
VIEWED FROM TOP

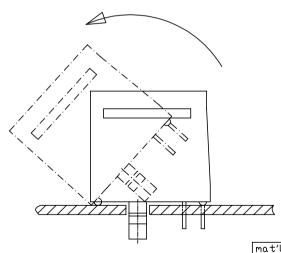
1.27 TYP

1.91

ø 3.25±0.08 (2X)

ø 0.76±0.08 (4X)

DIRECTION OF DISMOUNT



NOTES:

- P/N WITH DASH X4XX -NORMAL WAVE SOLDERING APPLICATION.
- 2 PACKAGING SPEC. GES-14-351. (USING TRAY).
- 3 SCRATCH MARKS ACCEPTABLE ON THESE SURFACES.
- 4 JACK IS FOR 1.57/.062 THICK PCB.
- 5 SHOULD THE JACK NEED TO BE DISMOUNTED FROM THE PCB. PLS REMOVE JACK AS PER RECOMMENDED METHOD HEREIN. (DETAIL A) NIPPING THE LEGS OF THE PEG TOGETHER IS DISALLOWED, OTHERWISE LEG BREAKAGE MAY OCCUR.
- 6 THESE DIMENSIONS ARE MEASURED FROM THE TOP OF THE PEG.
- 7 THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- 8 IF LF P/N PACKSGING MEETS GS-14-920 SPECIFICATION
- 9 THE HOUSING WILL WITHSTAND EXPOSURE TO 260° PEAK
 TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION
 WITH A 1.57mm MINIMUM THICK CIRCUIT BOARD
- (10) EQUIVALENT THICKNESS AU AND GXT PLATING HAVE SAME FUNCTION AND THEY ARE ALTERNATIVE BY THE CUSTOEMR.

JACK DISMOUNT METHOD

DETAIL A
NOTE 5

surface tolerance projection product family mat'l, code IS□1302 V ISD1101 ISD406 MOD JACK Specificatitle ltrecn nødr date toleraņces unless other 0.X±0.3 | NO4-0023 | D QIN | O6/07/04| mm 8 POS HORIZONTAL N04-0102 YS 11/23/04 0.XX±0.15 P.C.B. III MOD JACK ASSY scale2.0 0.XXX±0.05 N04-0109 YS 11/30/04 0°±2° dwg no sheet2of2 size NO8-0097 SH MMO 09/24/08 dr C L FENG 02/21/97 H ELX-N-010678 SH MAO 03/14/12 engr TONY CHIEN 02/21/97 61835 chr tony chien 02/21/97 appd Jenn TSAO 02/21/97 type Product Customer Drawing sheet revision index sheet

PDS: Rev :H3

В

form: A4mmXLc 1

2

STATUS:Released

ed Printed: Sep 1242013